



## IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,  
Assemblies, Related Materials and Processes

For rules and details of the IECQ visit [www.iecq.org](http://www.iecq.org)

# Schedule of Scope to Certificate of Approval Component Capability Approval

IECQ Certificate No.: C-IECQ BSI 05.0015

CB Certificate No.: E063/CA

Schedule Number: C-IECQ BSI 05.0015-S

Rev No.: 7

Revision Date: 2012/12/31

Page 1 of 1

<b>Manufacturer</b>	eXception PCB Limited		
<b>Board Types:</b>	Rigid Multilayer		BS CECC 23 300-003
	Rigid double-sided with plated through holes		BS CECC 23 200-003
	Rigid single & double-sided with plain holes		BS CECC 23 100-003
<b>Base Material:</b>	Epoxide Woven Glass		
<b>Board Size</b>	450 mm x 355 mm Maximum		BS EN 123 100, BS EN 123 200
	405 mm x 355 mm Maximum		BS EN 123 300
<b>Conductors:</b>	Minimum width: 100 $\mu\text{m}$ $\pm$ 25 $\mu\text{m}$		
	Minimum spacing: 100 $\mu\text{m}$ $\pm$ 25 $\mu\text{m}$		
<b>No. of layers:</b>	16 Maximum		
<b>Plated through hole diameter:</b>	0.6 mm Minimum	finished	for component mounting
	0.3 mm Minimum	drilled	via hole
<b>Aspect:</b>	8 : 1 Maximum		
<b>Finishes</b>	* Hot Air Solder Levelling		
	* Immersion Gold; Electroless Nickel		
	5 $\mu\text{m}$ Gold on Copper Edge Contacts		
	Liquid Photopolymer Solder Resist		
	Wet Film Solder Resist		
	Legend		

\* These finishes meet the solderability requirements.

This schedule is only valid in conjunction with the referenced Certificate of Approval  
This approval and any schedule(s) may only be reproduced in full.  
This approval is not transferable and remains the property of the issuing body.  
The Status and authenticity of this approval and any schedule(s) may be verified by visiting the  
Official IECQ Website. [www.iecq.org](http://www.iecq.org)

BSI, Kitemark Court Davy Avenue Knowlhill Milton Keynes MK5 8PP UK

